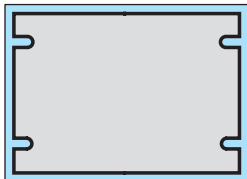
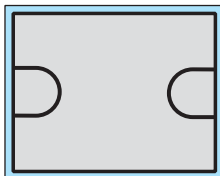


Accessories for solid state relays

THERMSTRATE® heat seal

Part numbers

1



Characteristics

Particular attention must be paid to thermal considerations in order to improve the reliability and power of solid state relays. It is extremely important to consider the quality of the interface between the relay and the heatsink (ROCs). Air pockets or gaps risk causing hot spots and a significant rise in temperature. Compared with the published thermal dissipation curves, performance is likely to be inferior or inconsistent. See the power curves and the description of heat transfer and of the heatsink presented in the corresponding individual technical data sheets.

We are pleased to offer cut-out pads of Thermstrate® thermal interface which replace messy and uneven heat transfer compounds. This pad is made of an aluminium substrate covered on each side with a "touch-dry" thermal compound. If the temperature exceeds 51°C, the thermal compound wetting action allows it to fill any gaps, while its natural capillary action draws it to the edge of the interface between the mating surfaces, thus preventing it spreading.

To order a supply of pads with the corresponding relay, please specify:

– For the G, GA5, GF and GT ranges

– For the 3-phase GA0 range and the GA3 range

Sold in packs of 25 (representing 1 lot) per part number.

Thermstrate is a registered trademark of Power Devices, Inc.

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